



Material Content Data Sheet



Sales Product Name				IPP80N06S4L-05		Issued		14. November 2014	
MA#				MA001055164					
Package				PG-TO220-3-1		Weight*		2035.25 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.393	0.17	0.17	1667	1667	
leadframe	non noble metal	iron	7439-89-6	0.816	0.04		401		
	inorganic material	phosphorus	7723-14-0	0.245	0.01		120		
wire	non noble metal	copper	7440-50-8	815.335	40.07	40.12	400608	401129	
	non noble metal	aluminium	7429-90-5	6.039	0.30	0.30	2967	2967	
encapsulation	organic material	carbon black	1333-86-4	8.918	0.44		4382		
	plastics	epoxy resin	-	98.096	4.82		48199		
	inorganic material	silicondioxide	60676-86-0	487.508	23.95	29.21	239533	292114	
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10545	10545	
plating	non noble metal	nickel	7440-02-0	0.244	0.01		120		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	400607	120	
solder	noble metal	silver	7440-22-4	0.074	0.00		36		
	non noble metal	tin	7440-31-5	0.059	0.00		29		
	non noble metal	lead	7439-92-1	2.822	0.14	0.14	1387	1452	
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		290		
	inorganic material	phosphorus	7723-14-0	0.177	0.01		87		
	non noble metal	copper	7440-50-8	589.466	28.96	29.00	289629	290006	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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